

Ver 3.0.0.1

1. First formal release
2. Support AG-AND flash
3. Add F6 "Erase Good" function

Ver 3.0.0.2

1. Change read file Window API from fgetc to ReadFile.
2. Fix copy file fail if multi-device run.
3. Add "Erase good blk before initial + MP + erase good blk" prescan option.
4. Change toolbar text color.
5. Remove "partition write sector" read sector check.
6. Add "Erase all blk before initial + MP + erase good blk" prescan option.
7. Assign maximum 20 blocks to extension zone 0 if select Toshiba single plane prescan option for Toshiba 70 nm MLC flash.
8. Fix if set public 1 area capacity to zero MP tool will show 0X94 error code when checking MBR/PBR/FAT.
9. Firmware change.

Ver 3.3.1.0

1. Enlarge the test status icon.
2. Modify "F10" QuickTest for two steps production.
3. Write the USB register 0x1074 (0xe0) and 0x1077 (0x14) after plug-in UFD.
4. Modify CIS offset value 0x37 (0xe0), 0x3a (0x14).
5. Add FP Cechk sensor function.
6. Modify BCD/FP/Other MLC flash tolerance ( 30 blks ), Ut163 toshiba single plane ( 30 blks ).
7. Solve "F6" Erase Good Blk error with Renesas flash.
8. Add medium density(483MB) of Renesas flash capacity option.
9. Add F8 Eject to turn off device LED.
10. Modify copy file function for multi-directory.

Ver 3.3.2.0

1. Solve ESP file problem.
2. Fix Vista UAC issue.

Ver 3.3.3.0

1. Flash capacity adjudgment for BCD.

Ver 3.4.1.0

1. Support Vista ReadyBoost for MLC.
2. Support 90% AG-AND flash.
3. Solve imanufacture code error.

Ver 3.4.2.0

1. Add "Auto function" for partition
2. Add "Full pattern" read/write stress function.
3. Support LUN size 0
4. Support 4pcs Renesas flash

Limitation:

- Not support Toshiba MLC
- Can't enable "partition ready only" of LUN0

Ver 3.4.3.0

1. Support partition size auto detect
2. Support LUN0 ready only
3. Support Toshiba MLC flash

Ver 3.5.1.0

1. Improve Hynix MLC single channel write performance
2. Hide "Eject function"

Ver 3.5.2.0

1. Fix capacity different between MP tool and BCD panel
2. Modify BCD K9HAG08U1M, K9HBG08U1M and TH58NVG4D4CTG00 capacity for special customer requirement

Ver 3.5.6.0

1. modify F5 Refresh button fail
2. Firmware change for BCD

Ver 3.6.1.0

1. Add K9F8G08U0M support
2. Add Micron MT29F32G08TAA, MT29F16G08QAA, MT29F8G08MAA support (8Gb MLC series)
3. Add Intel 29F8G08AAMB1 support (8Gb MLC)
4. Improve Vista Ready Boost performance

Ver 3.7.1.0

1. FP default select check sensor
2. Toshiba flash single plane issue
3. Nforce4 platform Winsat performance
4. FAT32 performance improvement
5. 8GB format time too long
6. Embedded tool version and manufacture date in flash
7. Improve MP tool stability at XP
8. Solve Vista autorun fail
9. Adjust IO driving control

Ver 3.7.4.0

1. re-write data when read count to a maximum number
2. Improve MLC 2 plan Copy Back performance

Ver 3.8.1.0

1. Modify capacity for both SLC/MLC flash
2. Add disable interleave function at MP tool
3. Fixed error , report bad block numbers of 4 chip Interleave mode  
(HY27UT084G2M,HY27UU088G5M,HY27UV08AG5M,HY27UW08BGFM)
4. Fixed error , inquiry command
5. Add Boot-disk option at MP tool
6. Enable interleave of Samsung K9K8G series

Ver 3.8.9.0

1. Micron flash timing set to 33 ns
2. Support Samsung SLC 4K page flash dual channel
3. Hynix 60nm flash test mode enable
4. Fix error, "other" setting load eep. file failed
5. Record block list at CIS

Ver 3.8.14.0

1. Rewrite show FlashId code.
2. Fix Force Single Plane will show wrong bad block number.
3. Mark MLC flash bad block index at first sector also.
4. Rewrite stress code. (2nd pass show error if 2 patterns selected )
5. Fix blank blk search. (block 0 fail issue)
6. Fix SN option coding error.

Ver 3.9.3.0

1. Input capacity tolerance instead of bad blk tolerance. ( 0 : default )
2. Fix FAT32 cluster 16K bytes. ( 32 logical sectors )
3. Fix MLC flash copy files low speed.
4. Modify rebuild function.
5. Add Capacity Tolerance BIN Select.
6. Add RSA flash option.

Ver 3.9.8.0

UT163 A1B

1. Solved Power cycling issue.
2. Add capacity BIN Select text box number.
3. Fix interleave enable & disable function.
4. Solved Toshiba 3D4CT BIN select size fail.
5. Delete "Dual mode disable" & "16-chips flash enable" at Flash Parameters function.
6. Add Flash:
  - Samsung K9G2G08U0M
  - Samsung K9LBG08U1M
  - Samsung K9HCG08U5M
  - Micron MT29F16G08QAA
  - Hynix HY27UF082G2B

Hynix HY27UF084G2B  
Hynix HY27UG088G5B  
Hynix HYUT088G2A

UT176 A2C

1. Modify MP size .
2. Solved Power cycling issue.
3. Add Flash:  
Micron MT29F16G08QAA  
Hynix HY27UF082G2B  
Hynix HY27UF084G2B  
Hynix HY27UG088G5B  
Hynix HYUT088G2A

Ver 3.9.12.0

1. Derive from 3.9.8.0
2. Fix UT176 A2C initial Current over 100mA.

Ver 3.9.25.0

1. Fix issue: Serial number will not be updated if launch MPTool with ESP file.
2. Update UT176 Q0A firmware(080215\_normal)
3. When hidden >0 and security is auto ,then pub1 is allow setting to 0
4. Add QFNdlg
5. Fix issue: Bin select setting was not saved when closing MPTool program.
6. Add Spansion flash:  
S19MN256P30TFP00  
S19MN512P30TFP00  
S19MN01GP30TFP00
7. LED ON/OFF option bug fixed(Remove "blink" option)
8. Toshiba flash show capacity error
9. Fix combo box display error after load the ESP file(\*.erp) .
10. Fix MPTool QFN Multi ports program fail.

Ver 3.9.29.0

1. Fix log file save site issue.
2. Fix stress option advance setting copy compare option issue.
3. Add LED blink function when device is idle.

Ver 3.9.30.0

1. Add Renesas 1/4 capacity(only for 4Gb).
2. Add a new option – “Format as Windows Size”

Ver 3.9.31.0

1. Derive from 3.9.30.0
2. Bin Select error
3. 0x10,0x11 bug fix on DeviceChange